



Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A0911-02**                      DATE: **20-Nov-2009**  
Product Affected: 13.5mm x 8.0mm FPBGA-176  
                                                (Green)  
                                                Refer to Attachment II for the affected part numbers  
Date Effective: **20-Feb-2010**

MEANS OF DISTINGUISHING CHANGED DEVICES:  
 Product Mark  
 Back Mark     Lot # will have a "CH" prefix.  
 Date Code  
 Other

Contact: PS Tow  
Title: Director, Product Assurance  
Phone #: (408) 284-8206  
Fax #: (408) 284-1450  
E-mail: [pstow@idt.com](mailto:pstow@idt.com)

Attachment:      Yes                       No

Samples: Please contact your local sales representative for  
sample request & availability.

**DESCRIPTION AND PURPOSE OF CHANGE:**

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

This notification is to advise our customers that IDT is adding Chipmos, Taiwan as an alternate assembly facility for 13.5mm x 8.0mm FPBGA-176, Green version. There is no change to the moisture performance of this package.

Attachment I details the qualification data for this change and Attachment II shows the affected list of part numbers.

**RELIABILITY/QUALIFICATION SUMMARY:**

Refer to qualification data shown in attachment I.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.  
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: \_\_\_\_\_                       *Approval for shipments prior to effective date.*  
Name/Date: \_\_\_\_\_                      E-Mail Address: \_\_\_\_\_  
Title: \_\_\_\_\_                              Phone# /Fax#: \_\_\_\_\_

**CUSTOMER COMMENTS:** \_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_                      DATE: \_\_\_\_\_



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT I - PCN # : A0911-02

**PCN Type:** Manufacturing Site - Alternate Assembly Location  
**Data Sheet Change:** None  
 No change in moisture sensitivity level (MSL)

#### Detail Of Change:

This notification is to advise our customers that IDT is adding Chipmos, Taiwan as an alternate assembly facility for 13.5mm x 8.0mm FPBGA-176, Green version. There is no change to the moisture performance of this package using the assembly material sets as listed in the below table.

#### Qualification Information and Qualification Data:

**Affected Packages:** 13.5mm x 8.0mm FPBGA-176 (AKG176)

**Assembly Material:** See Table below

Description	Existing	Add
Assembly Location	Amkor, Philippines; SPIL, Taiwan	Chipmos, Taiwan
Assembly Materials	Die Attach: Ablestik 2300, Ablestik 2000	Ablestik 2025D
	Wire: Au wire 0.8 mil	Au wire 0.8 mil
	Mold Compound: EME-G770, GE100LFCS	KE-G1250
	Substrate: BT Resin HL832NX, AUS308	BT Resin HL832NX, AUS308
	Solder Balls: Sn96.5/Ag3.0/Cu0.5 (Green)	Sn96.5/Ag3.0/Cu0.5 (Green)



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT I - PCN # : A0911-02

#### Qualification Test Plans and Results :

**IDT Qual Plan#:** P09-08-06  
**Qual Vehicle:** 13.5mm x 8.0mm FPBGA-176 ( 3 lots )

Test Description	Test Method	Test Results (SS / Rej)		
		Lot 1	Lot 2	Lot 3
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 100 Hrs)	JESD22-A110-B	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 500 Cyc)	JESD22-A104-B	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 500 Hrs)	JESD22-A103-B	25/0	25/0	25/0

Note:

\* Test requires moisture pre-conditioning sequence per JESD22-A113 and will use the existing moisture sensitivity level that has been qualified for this material set.



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## **PRODUCT/PROCESS CHANGE NOTICE (PCN)**

### **ATTACHMENT II - PCN # : A0911-02**

#### **Affected Part Number**

<b>Part Number</b>	<b>Part Number</b>	<b>Part Number</b>	<b>Part Number</b>
SSTE32882HLBAKG	SSTE32882HLBAKG8	SSTE32882TNA1AKG	SSTE32882TNA1AKG8